Vishay Semiconductors

HEXFRED[®], Ultrafast Soft Recovery Diode, 2 x 15 A



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Base common cathode 2 1 2 3 Anode Common cathode Anode

PRIMARY CHARACTERISTICS					
I _{F(AV)}	2 x 15 A				
V _R	600 V				
V _F at I _F	1.2 V				
t _{rr} (typ.)	19 ns				
T _J max.	150 °C				
Package	D ² PAK (TO-263AB)				
Circuit configuration	Common cathode				

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

DESCRIPTION

VS-HFA30TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{BBM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Cathode to anode voltage	V _R		600	V				
Maximum continuous forward currentper leg	1_	T _C = 100 °C	15					
per device	- IF	1C = 100 C	30	А				
Single pulse forward current	I _{FSM}		150	A				
Maximum repetitive forward current	I _{FRM}		60					
Maximum power dissipation	Р	T _C = 25 °C	74	°C				
Maximum power dissipation	PD	T _C = 100 °C	29	0				
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	W				

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ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25 \text{ °C}$ unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V_{BR}	I _R = 100 μA		600	-	-		
	V _{FM}	I _F = 15 A	See fig. 1	-	1.3	1.7	V	
Maximum forward voltage		I _F = 30 A		-	1.5	2.0		
		I _F = 15 A, T _J = 125 °C		-	1.2	1.6		
Maximum reverse		$V_{R} = V_{R}$ rated	See fig. 2	-	1.0	10		
leakage current	I _{RM}	$T_J = 125 \text{ °C}, V_R = 0.8 \text{ x } V_R \text{ rated}$	See fig. 2	-	400	1000	μA	
Junction capacitance	CT	V _R = 200 V	See fig. 3	-	25	50	pF	
Series inductance	L _S	Measured lead to lead 5 mm from p	ackage body	-	8.0	-	nH	

DYNAMIC RECOVERY CHARACTERISTICS PER LEG ($T_J = 25$ °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
	t _{rr}	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200$	A/μs, V _R = 30 V	-	19	-			
Reverse recovery time See fig. 5, 10	t _{rr1}	T _J = 25 °C		-	42	60	ns A nC		
000 lig. 0, 10	t _{rr2}	T _J = 125 °C	I _F = 15 A dI _F /dt = 200 A/µs V _R = 200 V	-	70	90			
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	4.0	6.0			
See fig. 6	I _{RRM2}	T _J = 125 °C		-	6.5	10			
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	80	180			
See fig. 7	Q _{rr2}	T _J = 125 °C		-	220	450			
Peak rate of fall of recovery current during t _b See fig. 8	dl _{(rec)M} /dt1	T _J = 25 °C		-	188	-	A/µs		
	dl _{(rec)M} /dt2	T _J = 125 °C		-	160	-			

THERMAL - MECHANICAL SPECIFICATIONS PER LEG								
PARAMETER	ER SYMBOL TEST CONDITIONS				MAX.	UNITS		
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Junction to case, single leg conducting	— R _{thJC}		-	-	1.7			
Junction to case, both legs conducting	ПthJC		-	-	0.85	K/W		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80			
Weight			-	2.0	-	g		
weight			-	0.07	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style D ² PAK (TO-263AB)		HFA30TA60CS				



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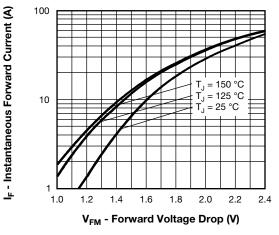


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

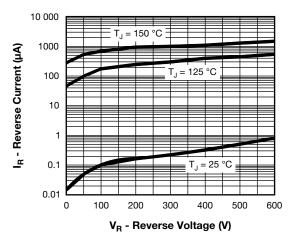


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

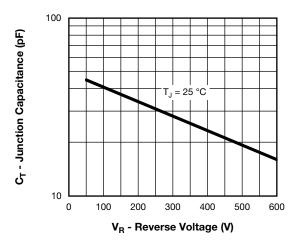
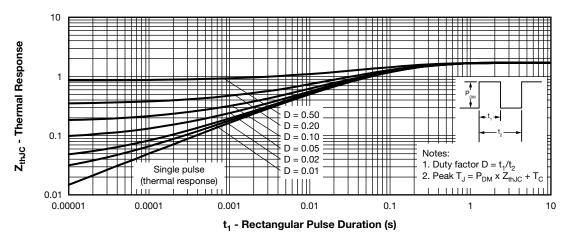
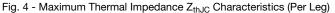


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)





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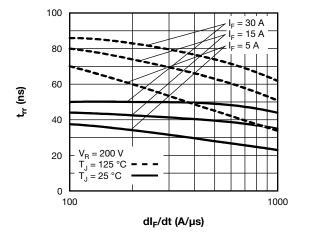


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

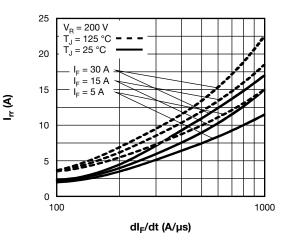


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

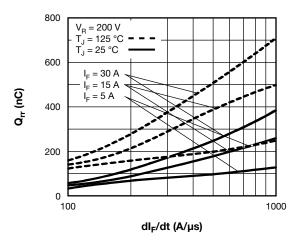


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

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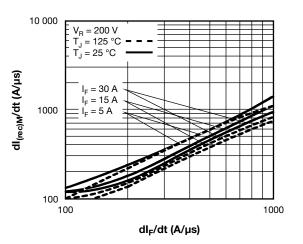


Fig. 8 - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)

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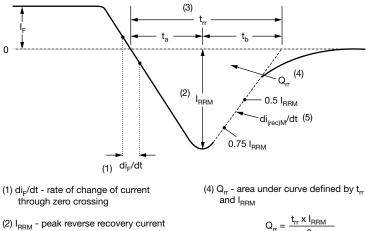
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(3) $\rm t_{\rm rr}$ - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 $I_{\rm RRM}$ and 0.50 $I_{\rm RRM}$ extrapolated to zero current.

$$Q_{rr} = \frac{l_{rr} \times l_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	VS-	HF	Α	30	ТА	60	С	S	L	-M3
	1	2	3	4	5	6	7	8	9	10
	1 - Vishay Semiconductors product									
	2	- HEX	XFRED [@]	[®] family						
	3	- Pro	cess de	signato	r: A = ele	ectron i	rradiate	d		
	4	- Cur	Current rating (30 = 30 A)							
	5	- Pac	kage ou	utline (T	A = TO-	220, 3 I	eads)			
	6	- Vol	tage rati	ing (60 =	= 600 V))				
	7	- Circ	cuit conf	iguratio	n (C = c	ommon	cathod	e)		
	8	- S=	D ² PAK	(TO-26	3AB)					
	9	- • N	one = tu	ıbe						
		• L = tape and reel (left oriented)								
	_	• R = tape and reel (right oriented)								
	10			ntal digit						
		-M3	s = halog	gen-free	, RoHS	-compli	ant, and	l termin	ation le	ad (Pb)-f



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ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-HFA30TA60CS-M3	50	Antistatic plastic tube					
VS-HFA30TA60CSR-M3	800	13" diameter reel					
VS-HFA30TA60CSL-M3	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96164				
Part marking information	www.vishay.com/doc?95444				
Packaging information	www.vishay.com/doc?96424				

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D²PAK

DIMENSIONS in millimeters and inches



ota	ted	90	°C
<u>S</u>	cale	<u>ə:</u> 8	:1

SYMBOL	MILLIM	ETERS	INC	HES	NOTES	
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.06	4.83	0.160	0.190		
A1	0.00	0.254	0.000	0.010		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
с	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	

SYMBOL	MILLIMETERS		INCHES		NOTES
STNDUL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994

(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

(3) Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

(5) Datum A and B to be determined at datum plane H

(6) Controlling dimension: inches

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-263AB

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